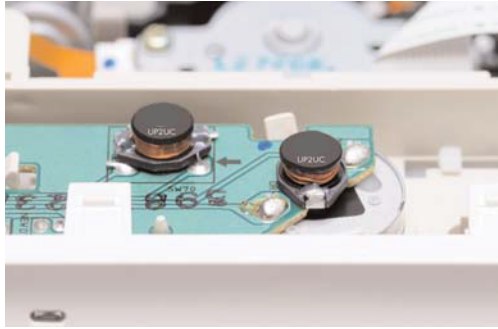


UP2UC

UNI-PAC™ drum core power inductors



Product features

- 12.7 mm x 9.5 mm x 5.21 mm drum core
- Inductance range from 1.0 μ H to 1000 μ H
- Current range from 0.30 A to 9.0 A
- Ferrite core material

Applications

- Desktop computer
- Workstations/servers
- DVD Players
- Portable power devices
- Base stations
- Industrial power supplies
- Output filter chokes
- Test equipment instrumentation
- Buck or boost inductor

Environmental data

- Storage temperature range (component):
-40 °C to +125 °C
- Operating temperature range: -40 °C to +125 °C
(ambient plus self-temperature rise)
- Solder reflow temperature:
J-STD-020 (latest revision) compliant



Product specifications

| Part Number ⁵ | OCL ¹ μH ± 20% | I _{rms} ² (A) | I _{sat} ³ (A) @ +25 °C | SRF MHz Typical | DCR mΩ @ +20 °C Typical | DCR mΩ @ +20 °C Maximum | K-factor ⁴ |
|--------------------------|------------------------------|--------------------------------------|---|--------------------|----------------------------|----------------------------|-----------------------|
| UP2UC-1R0-R | 1.0 | 6.8 | 9.0 | 100 | 4.0 | 9.0 | 216 |
| UP2UC-1R5-R | 1.5 | 6.4 | 8.0 | 90.0 | 4.4 | 10.0 | 177 |
| UP2UC-2R2-R | 2.2 | 6.1 | 7.0 | 80.0 | 5.8 | 12.0 | 130 |
| UP2UC-3R3-R | 3.3 | 5.4 | 6.4 | 65.0 | 9.9 | 15.0 | 114 |
| UP2UC-4R7-R | 4.7 | 4.8 | 5.4 | 45.0 | 12.0 | 18.0 | 92.52 |
| UP2UC-6R8-R | 6.8 | 4.4 | 4.6 | 38.0 | 25.8 | 27.0 | 77.72 |
| UP2UC-100-R | 10.0 | 3.9 | 3.8 | 30.0 | 25.9 | 38.0 | 62.68 |
| UP2UC-150-R | 15.0 | 3.1 | 3.0 | 27.0 | 35.4 | 46.0 | 49.82 |
| UP2UC-220-R | 22.0 | 2.7 | 2.6 | 19.0 | 55.9 | 85.0 | 41.34 |
| UP2UC-330-R | 33.0 | 2.1 | 2.0 | 15.0 | 81.6 | 100 | 34.09 |
| UP2UC-470-R | 47.0 | 1.8 | 1.6 | 12.0 | 120 | 140 | 29.00 |
| UP2UC-680-R | 68.0 | 1.5 | 1.4 | 10.0 | 145 | 200 | 24.59 |
| UP2UC-101-R | 100 | 1.3 | 1.2 | 9.0 | 211 | 280 | 20.89 |
| UP2UC-151-R | 150 | 1.0 | 1.0 | 6.0 | 347 | 400 | 15.80 |
| UP2UC-221-R | 220 | 0.80 | 0.80 | 5.0 | 491 | 610 | 13.04 |
| UP2UC-331-R | 330 | 0.60 | 0.60 | 4.5 | 750 | 1020 | 10.85 |
| UP2UC-471-R | 470 | 0.50 | 0.50 | 3.5 | 1188 | 1270 | 9.39 |
| UP2UC-681-R | 680 | 0.40 | 0.40 | 2.5 | 1811 | 2020 | 7.56 |
| UP2UC-102-R | 1000 | 0.30 | 0.30 | 2.0 | 2757 | 3000 | 6.13 |

1 Open Circuit Inductance (OCL) Test Parameters: 100 kHz, 0.25 V_{rms}, 0.0 Adc

2 I_{rms}: DC current for an approximate ΔT rise of 40 °C without core loss. Derating is necessary for AC currents. PCB layout, trace thickness and width, air-flow and proximity of other heat generating components will affect the temperature rise. It is recommended the part temperature not exceed +125 °C under worst case operating conditions verified in the end application.

3 I_{sat}: Peak current for approximately 7.5% rolloff at +25 °C.

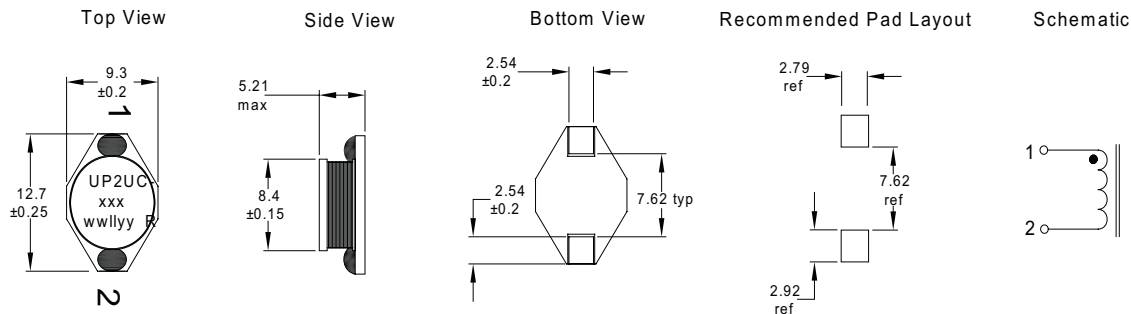
4 K-factor: Used to determine B_{p-p} for core loss (see graph). B_{p-p} = K * L * ΔI, B_{p-p}: (Gauss),

K: (K-factor from table), L: (inductance in μH), ΔI (peak-to-peak ripple current in amps).

6 Part Number Definition: UP2UCU-xxx-R

- UP2UCU = Product code and size
- xxx= Inductance value in μH, R = decimal point. If no R is present, then third digit equals the number of zeros.
- "-R" suffix = RoHS compliant

Dimensions-mm



Part Marking: UP2UC

xxx = Inductance value in μH (R = Decimal point). If no "R" is present, then the third digit equals the number of zeros.

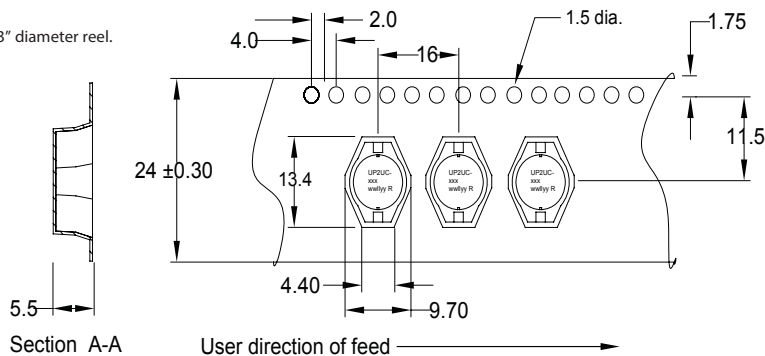
wwlllyy = Date code

R = Revision level

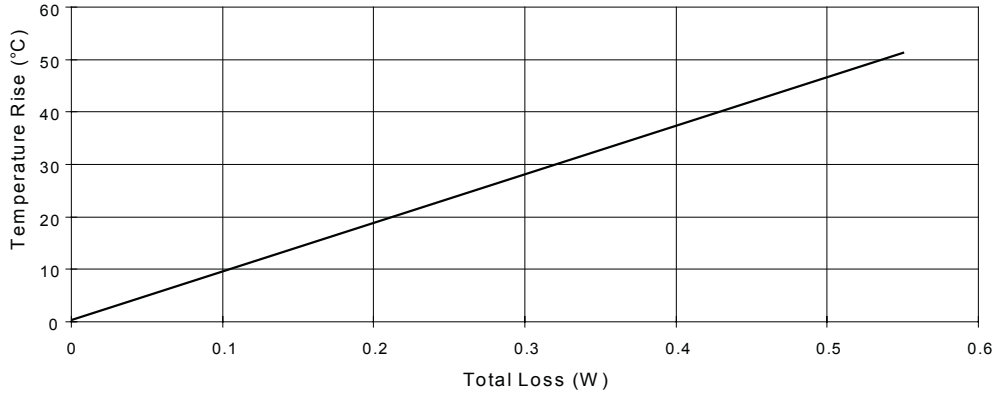
Tolerances are ±0.254 mm unless otherwise specified.
Do not route traces or vias underneath the inductor

Packaging information-mm

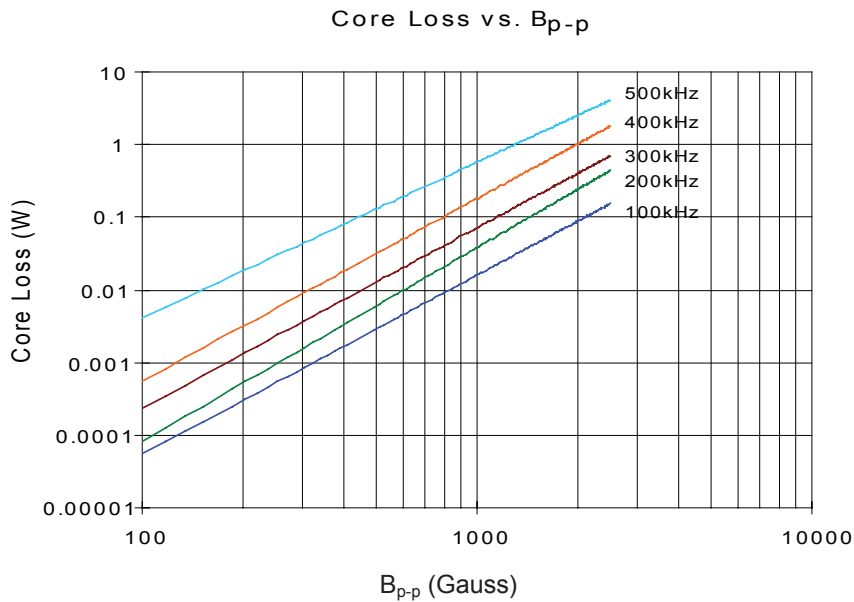
Supplied in tape-and-reel packaging, 600 parts per reel, 13" diameter reel.



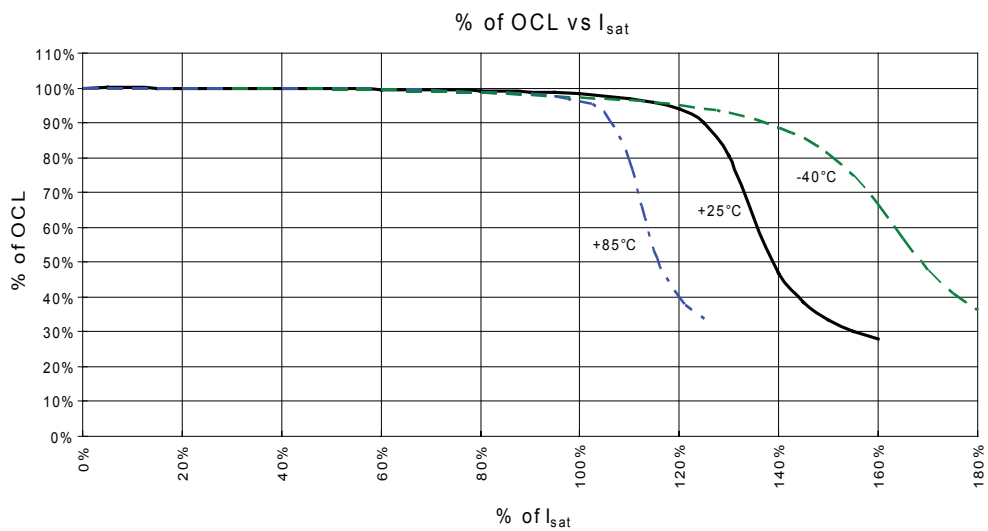
Temperature rise vs total loss



Core loss vs Bp-p



Inductance characteristics



Solder Reflow Profile

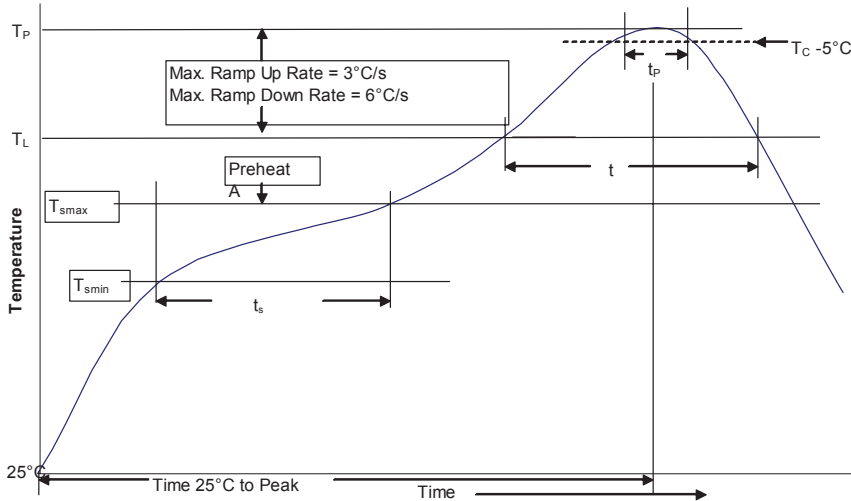


Table 1 - Standard SnPb Solder (T_c)

| Package Thickness | Volume mm^3 <350 | Volume mm^3 ≥ 350 |
|---------------------|---------------------------|---------------------------------|
| <2.5mm | 235°C | 220°C |
| $\geq 2.5\text{mm}$ | 220°C | 220°C |

Table 2 - Lead (Pb) Free Solder (T_c)

| Package Thickness | Volume mm^3 <350 | Volume mm^3 350 - 2000 | Volume mm^3 >2000 |
|-------------------|---------------------------|---------------------------------|----------------------------|
| <1.6mm | 260°C | 260°C | 260°C |
| 1.6 - 2.5mm | 260°C | 250°C | 245°C |
| >2.5mm | 250°C | 245°C | 245°C |

Reference JDEC J-STD-020

| Profile Feature | Standard SnPb Solder | Lead (Pb) Free Solder |
|--|----------------------|-----------------------|
| Preheat and Soak | | |
| • Temperature min. (T_{smin}) | 100°C | 150°C |
| • Temperature max. (T_{smax}) | 150°C | 200°C |
| • Time (T_{smin} to T_{smax}) (t_s) | 60-120 Seconds | 60-120 Seconds |
| Average ramp up rate T_{smax} to T_p | 3°C/ Second Max. | 3°C/ Second Max. |
| Liquidous temperature (T_L) | 183°C | 217°C |
| Time at liquidous (t_L) | 60-150 Seconds | 60-150 Seconds |
| Peak package body temperature (T_p)* | Table 1 | Table 2 |
| Time (t_p)** within 5 °C of the specified classification temperature (T_c) | 20 Seconds** | 30 Seconds** |
| Average ramp-down rate (T_p to T_{smax}) | 6°C/ Second Max. | 6°C/ Second Max. |
| Time 25°C to Peak Temperature | 6 Minutes Max. | 8 Minutes Max. |

* Tolerance for peak profile temperature (T_p) is defined as a supplier minimum and a user maximum.

** Tolerance for time at peak profile temperature (t_p) is defined as a supplier minimum and a user maximum.

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- Подбор оптимального решения, техническое обоснование при выборе компонента;
- Подбор аналогов;
- Консультации по применению компонента;
- Поставка образцов и прототипов;
- Техническая поддержка проекта;
- Защита от снятия компонента с производства.



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